ABSTRACT OF THE DISCLOSURE

ADHESIVE SHEET FOR PRODUCING SEMICONDUCTOR DEVICE, SEMICONDUCTOR DEVICE THEREWITH, AND MANUFACTURING METHOD THEREFOR

An adhesive sheet (10) being strippably adhered to the lead frame or the wiring board, for manufacturing a semiconductor device of the present invention, which includes the heat-resistant base material and the adhesive layer (12) on one surface of the heat-resistant base material, wherein the adhesive layer (12) contains the thermosetting resin (a) and the strippability imparting component (b).

Figure 1